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X Ray BGA machine use - detecting bga PCB

www.seamarkxray.com

BGA- Ball array package, which is a highly integrated package, uses array solder balls on the bottom of the package substrate to interconnect the I/O terminals of the circuit with the printed circuit board PCB. The quality of the BGA soldering has a large impact on the packaged device.

X Ray BGA machine use :

Since the packaged product cannot be visually inspected, X Ray inspection BGA machine, ultrasonic can detect the quality. The most commonly used tool is X-RAY BGA machine, which not only has the function of visual inspection, but also saves the image for analysis , area measurements can be made on the contours of product defects.

BGA solder joint inspection application:

IC, PCBA, LED, lithium battery, IGBT, etc. Object detection: For chip size measurement, chip position, cavity, lead frame, wire, open circuit of connection line, short circuit, abnormal connection, ceramic capacitor structure, trace , solder joint holes, poor molding, bridging, tombstoning, insufficient solder / excess solder, component tin area ratio, device missing.

Noted: Seamark ZM, We want to support some distributor to attend this exhibition to open the market.

And plans to participate in the following exhibitions, welcome dealers, agents , distributor to discuss related matters.

ExpoElectronica/Electrontech 2019 Russia 2019 4.15-17

NEPCON Korea 2019 5.15-17

NEPCON Thailand 2019 6.19-22

NEPCON Vietnam 2019 9.11-13

EP India 2019 9.25-27

Electronica 2019 Germany 2019.11.12-15

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X Ray machine的用途-检测bga线路板

BGA全称焊球阵列封装，是一种高集成的封装方式，在封装基板底部采用阵列焊球作为电路的I/O端与印刷线路板PCB互连，BGA的焊接质量对产品封装器件有很大的影响。

但由于封装后的产品无法从外观上进行检测作业，往往需要借助一些技术手段来达到检测的目的，如X光检测BGA，超声波，但最常用的当属X-RAY，其不仅具有可视化检测的作用，还能保存检测后

的图像并后期分析，可以对产品缺陷的轮廓进行一定的勾勒和面积测算。

X光检测设备利用X光透过被检测物体后衰减（不同材料对光的吸收度不同），由射线接收/转换装置接收并转换成信号，探测器将检测后的影像传输至显示器屏幕上，技术员可以及时的分析出产品的缺陷。

BGA焊点检测应用:

IC，PCBA，LED，锂电池，IGBT等等物件检测: 用于芯片大小量测、芯片位置、空洞、导线架、打线、连接线路的开路、短路、不正常连接、陶瓷电容结构，走线、焊点孔洞、成型不良、桥连、立碑、焊料不足/过剩、组件吃锡面积比例、器件漏装。